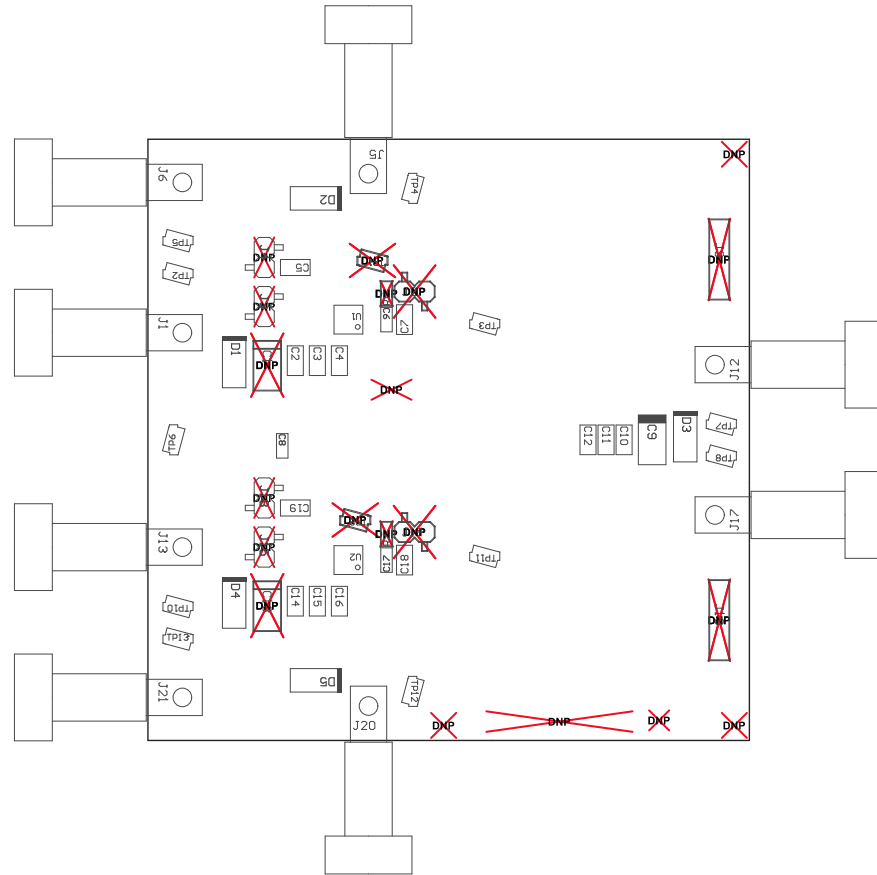


Z230 ~~DNP~~ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

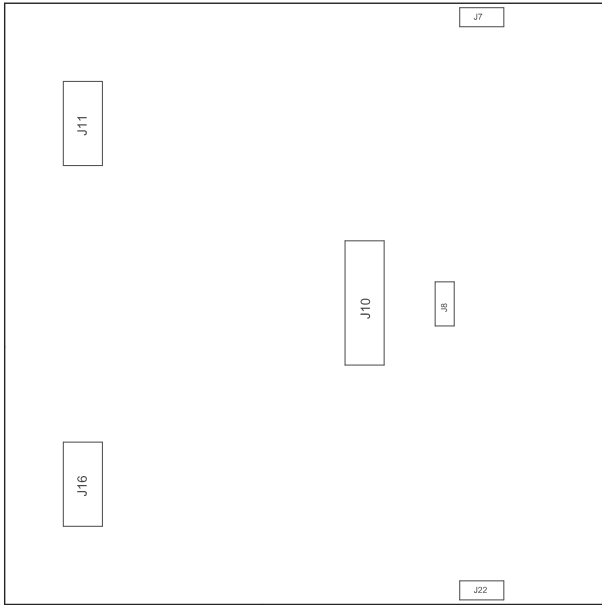
Z220 ~~DNP~~ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z210 ~~DNP~~ These assemblies are ESD sensitive, ESD precautions shall be observed.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
	TID #: A-01232		
PLOT NAME = Top Assembly Drawing	GENERATED : 7/7/2017	9:14:47 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01232	REV: B	SUN REV: Not In VersionControl
	TID #: A-01232		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/7/2017	9:14:48 AM	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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